


**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MDG/23/14015	
1.3 Title of PCI	AMKOR (Taiwan) STM32F412RxY6TR WLSCP package pin1 orientation in carrier tape harmonization	
1.4 Product Category	STM32F412RGY6TR STM32F412REY6TR	
1.5 Issue date	2023-04-26	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

**3. Change**

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Finished product and Wafer Storage procedure	AMKOR ATT (Taiwan)

**4. Description of change**

	Old	New
4.1 Description	Current situation STM32F412RGY6TR: pin1 top right STM32F412REY6TR: pin1 top right or top left	New situation STM32F412RGY6TR: changed to Pin1 top left STM32F412REY6TR: changed to Pin1 top left
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Die orientation in carrier tape harmonized to pin 1 top left Bill Of Material : No Change Package : no change Carrier tape : no change Marking : No change	

**5. Reason / motivation for change**

5.1 Motivation	Pin1 top harmonization to Pin1 top left
5.2 Customer Benefit	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

6.1 Description	tracability ensure by ST internal tools
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**7. Timing / schedule**

7.1 Date of qualification results	2023-03-17
7.2 Intended start of delivery	2023-03-17
7.3 Qualification sample available?	Not Applicable

**8. Qualification / Validation**

8.1 Description	14015 MDG-GPM-qualification.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-04-26

9. Attachments (additional documentations)		
14015 Public product.pdf 14015 MDG-GPM-qualification.pdf 14015 PCN14015_Additional information.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F412REY6TR	
	STM32F412RGY6TR	

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## Public Products List

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**PCI Title :** AMKOR (Taiwan) STM32F412RxY6TR WLSCP package pin1 orientation in carrier tape harmonization

**PCI Reference :** MDG/23/14015

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F412REY6TR	STM32F412RGY6PTR	STM32F412RGY6TR
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# **PCI 14015 AMKOR (Taiwan) STM32F412RxY6TR WLSCP package pin1 orientation in carrier tape harmonization**

## **Qualification Report**

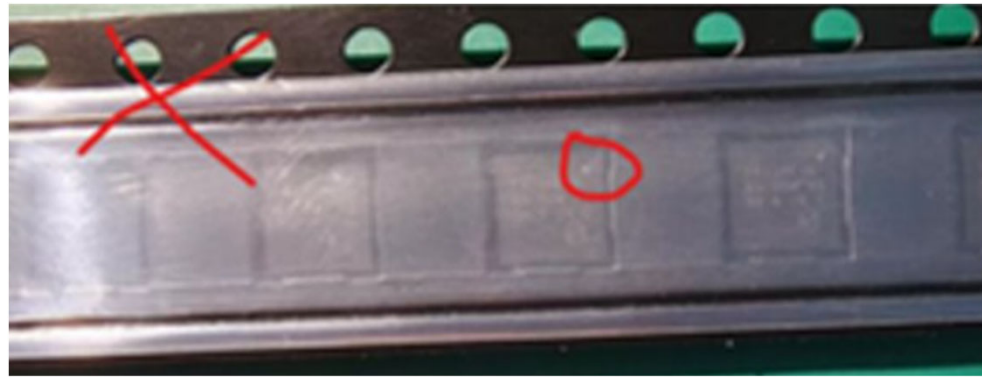
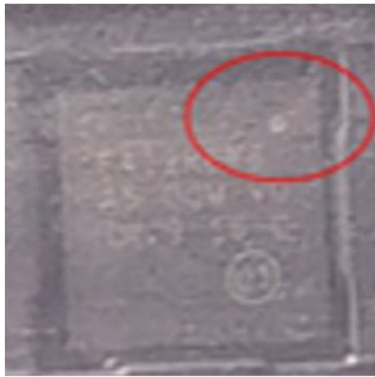
Mar 17th 2023

MDG GPM Product Test Engineering Department

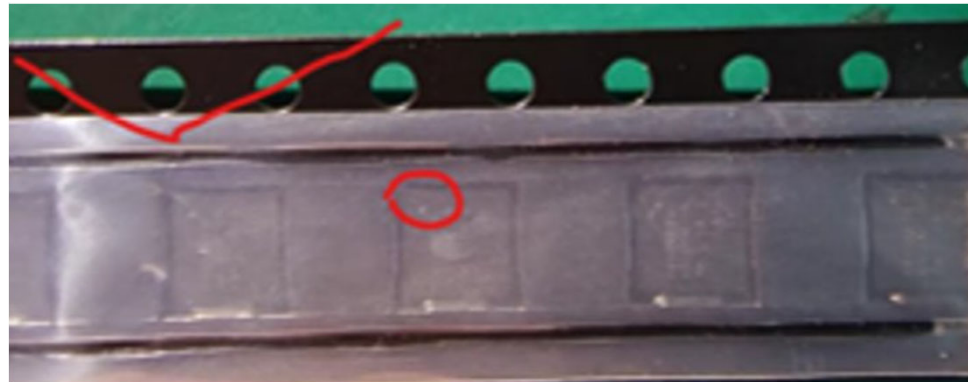


# AMKOR WLCSP Package mis-orientation of Pin1 in carrier tape

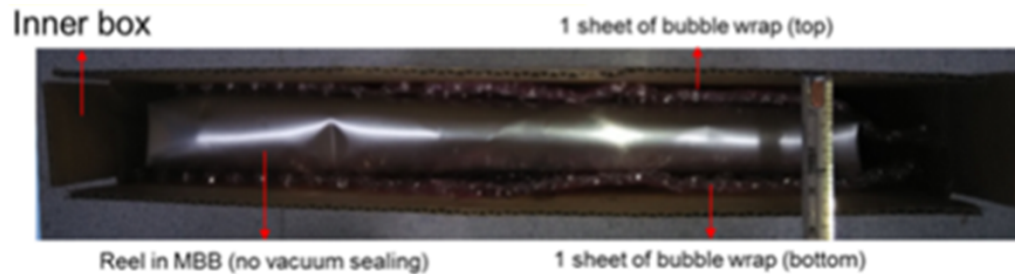
- Before



- After



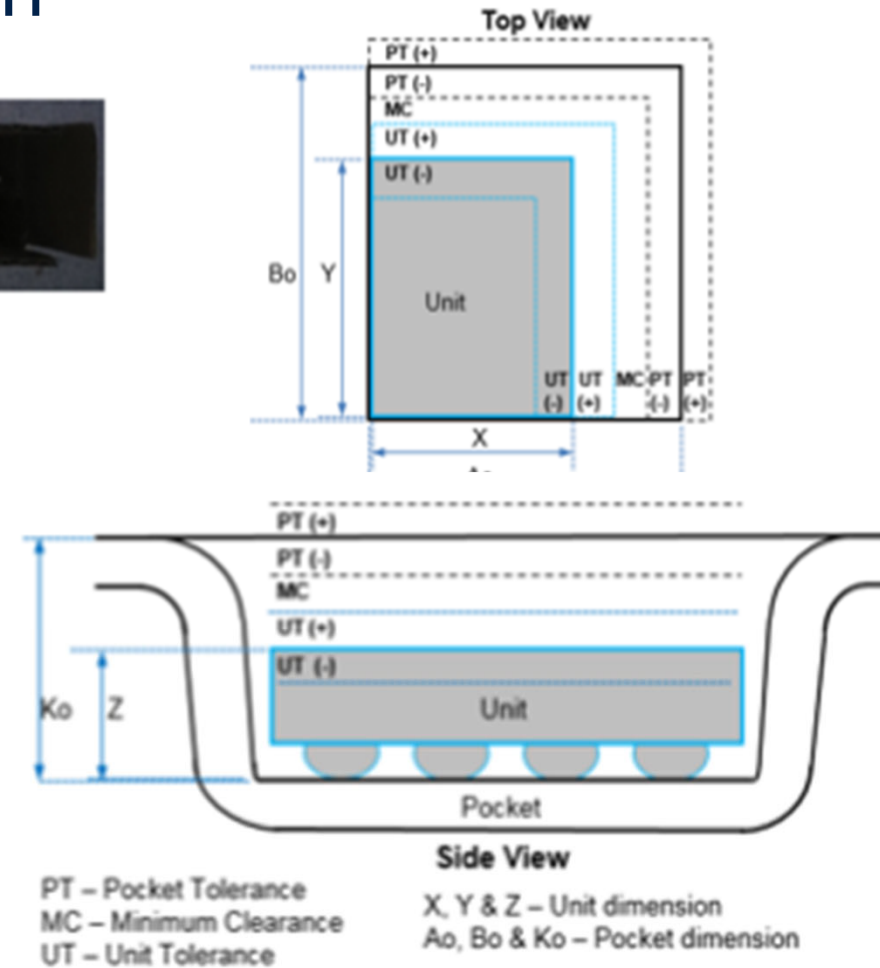
# Risk assessment and conclusion



- Carrier Tape fit analysis on orientation top left
  - Risk assessment done
  - Minimum (50 um) and Maximum clearance meet with pin1 top left
  - Note that clearance are meet also with pin1 top right.
  - No risk to produce on any of both orientation.
- Conclusion : No concern on the Fit Analysis between pocket size (Ao, Bo, Ko) & die size (X,Y,Z).



(a) Unit & Pocket Dimension





# Legal Information



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**AMKOR (Taiwan) STM32F412REY6TR and STM32F412RGY6TR  
WLSCP package pin1 orientation in carrier tape  
harmonization**

**MDG – General Purpose Microcontrollers (GPM) sub-group**

Assembly site	Current orientation	New orientation
	Two possible orientations for Pin 1	Harmonized position Pin 1 Top left
Pin 1 orientation example within the carrier tape	 <p>Top right</p>	 <p>Top left</p>
	 <p>Top left</p>	

**What is the change?**

There is no Bill Of Material change. Package is unchanged, Carrier tape unchanged, Marking unchanged. Only Die orientation is harmonized to top left inside the carrier tape.

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